U.S. Pat. Appl. Ser. No. 10/566,811 Attorney Docket No. 10191/4496 Reply to Office Action of October 29, 2009

## **AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **LISTING OF THE CLAIMS:**

- 1-8 (Canceled).
- 9. (Currently Amended) A press-fit diode, comprising:
  - a diode chip;
- a base contact for pressing the press-fit diode into a substrate, wherein the base contact is attached to the diode chip and forms a first terminal of the press-fit diode; and
- a wire contact which forms a second terminal of the press-fit diode, wherein the wire contact is attached to the diode chip and is at least partially provide with a silver layer, wherein the silver layer is directly applied on a nickel layer.
- 10. (Previously Presented) The press-fit diode as recited in claim 9, wherein a section of the wire contact attached to the diode chip is not provided with the silver layer.
- 11. (Previously Presented) The press-fit diode as recited in claim 10, wherein the base contact is not provided with a silver layer.
- 12. (Canceled).
- 13. (Currently Amended) A method for manufacturing a press-fit diode, comprising: providing a diode chip;

providing a base contact configured for pressing the press-fit diode into a substrate, wherein the base contact forms a first terminal of the press-fit diode;

providing a wire contact which forms a second terminal of the press-fit diode, wherein the wire contact is at least partially provided with a silver layer, which is directly applied on a nickel layer; and

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fixedly connecting the wire contact, the base contact, and the diode chip to one another.

- 14. (Previously Presented) The method as recited in claim 13, wherein a section of the wire contact attached to the diode chip is not provided with the silver layer.
- 15. (Previously Presented) The method as recited in claim 13, wherein the base contact is not provided with a silver layer.
- 16. (Previously Presented) The method as recited in claim 14, wherein the base contact is not provided with a silver layer.
- 17. (Currently Amended) The method as recited in claim 13, wherein the wire contact is made of copper, and wherein the wire contact is further provided with a has the nickel layer on which the silver layer is applied.
- 18. (Currently Amended) The method as recited in claim 14, wherein the wire contact is made of copper, and wherein the wire contact is further provided with a <u>has the</u> nickel layer on which the silver layer is applied.
- 19. (New) The press-fit diode as recited in claim 9, wherein the silver layer is applied before the press-fit diode is assembled.
- 20. (New) The press-fit diode as recited in claim 9, wherein a region for attaching the diode chip is recessed.
- 21. (New) The press-fit diode as recited in claim 9, wherein the wire contact is inserted in a rack with a wire shaft pointing downward, and wherein the wire shaft is immersed in an electroplating vat.
- 22. (New) The press-fit diode as recited in claim 9, wherein a central section of the press-fit diode is sheathed in plastic to protect the diode chip.

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- 23. (New) The press-fit diode as recited in claim 9, wherein the press-fit diode is electroplated in bulk in a drum process.
- 24. (New) The method as recited in claim 13, further comprising: applying the silver layer before the press-fit diode is assembled.
- 25. (New) The method as recited in claim 13, wherein a region for attaching the diode chip is recessed.
- 26. (New) The method as recited in claim 13, further comprising: inserting the wire contact in a rack with a wire shaft pointing downward; and immersing the wire shaft in an electroplating vat.
- 27. (New) The method as recited in claim 13, further comprising: sheathing a central section of the press-fit diode to protect the diode chip.
- 28. (New) The method as recited in claim 13, wherein the press-fit diode is electroplated in bulk in a drum process.
- 29. (New) The press-fit diode as recited in claim 9, wherein the silver layer is applied before the press-fit diode is assembled, wherein a region for attaching the diode chip is recessed, wherein the wire contact is inserted in a rack with a wire shaft pointing downward, wherein the wire shaft is immersed in an electroplating vat, wherein a central section of the press-fit diode is sheathed in plastic to protect the diode chip, and wherein the press-fit diode is electroplated in bulk in a drum process
- 30. (New) The method as recited in claim 13, further comprising: inserting the wire contact in a rack with a wire shaft pointing downward; immersing the wire shaft in an electroplating vat. wherein a region for attaching the diode chip is recessed; and

sheathing a central section of the press-fit diode to protect the diode chip; wherein the press-fit diode is electroplated in bulk in a drum process.